

## ABSTRACT

A laminate which is advantageously used as an insulating layer for electronic package application and as  
5 an adhesive film for fixing a semiconductor wafer for semiconductor device application, laminates comprising the same and a process for manufacturing the above laminate.

The laminate (I) comprises a base layer (A) and an adhesive layer (B) formed on one side or both sides of the  
10 layer A, the layer A is a film made of (A-1) a specific wholly aromatic polyimide ( $PI^{A-1}$ ) or (A-2) a specific wholly aromatic polyamide ( $PA^{A-2}$ ); and the layer B comprises (B-1) a specific wholly aromatic polyimide ( $PI^{B-1}$ ), (B-2) a specific wholly aromatic polyamide ( $PA^{B-2}$ ), or (B-3) a specific resin  
15 composition ( $RC^{B-3}$ ) comprising a wholly aromatic polyimide ( $PI^{B-3}$ ) and a specific wholly aromatic polyamide ( $PA^{B-3}$ ), laminates comprising the same and a process for manufacturing the above laminate.